

ULTRA-LOW IMPEDANCE POWER
INTERCONNECTION SYSTEM FOR ELECTRONIC PACKAGES

ABSTRACT OF THE DISCLOSURE

5 A power interconnection system comprising a plurality of z-axis compliant
connectors passing power and ground signals between a first circuit board to a second circuit
board is disclosed. The interconnection system provides for an extremely low impedance
through a broad range of frequencies and allows for large amounts of current to pass from
one substrate to the next either statically or dynamically. The interconnection system may be
10 located close to the die or may be further away depending upon the system requirements.
The interconnection may also be used to take up mechanical tolerances between the two
substrates while providing a low impedance. interconnect.

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